



Material Content Data Sheet



Sales Product Name		IPB80P03P4L-04		Issued		29. August 2013		
MA#		MA000462564						
Package		PG-TO263-3-2		Weight*		1463.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	0.28	0.28	2754	2754
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		583	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175	
	non noble metal	copper	7440-50-8	851.691	58.20	58.28	582127	582885
wire	non noble metal	aluminium	7429-90-5	5.701	0.39	0.39	3897	3897
encapsulation	organic material	carbon black	1333-86-4	8.812	0.60		6023	
	plastics	epoxy resin	-	96.929	6.63		66251	
	inorganic material	silicondioxide	60676-86-0	481.710	32.92	40.15	329247	401521
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6600	6600
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	noble metal	silver	7440-22-4	0.080	0.01		55	
	non noble metal	tin	7440-31-5	0.064	0.00		44	
	non noble metal	lead	7439-92-1	3.055	0.21	0.22	2088	2187
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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